ABSTRACT

A wiring method is provided, in which a wire conductor is stuck on a surface of a substrate by causing a three-dimensional relative movement between a wiring head (2) for guiding the wire conductor (5) and the substrate (11) such that the wiring head relatively moves along an adhesive layer (12) on the surface of the substrate and the wiring head and the adhesive layer intermittently come close to each other for point contact. A wiring apparatus for carrying out the wiring method includes a table (1) for supporting the substrate, a wiring head arranged for reciprocating motion between a close position in which the wiring head can be in point contact with the adhesive layer and a distant position in which the wiring head is most distant from the adhesive layer, and a moving mechanism (3) for causing a translational motion of the wiring head along the surface of the substrate under the control of a control section (4). The wire conductor is stuck onto the surface of substrate point by point, to be laid thereon, whereby a planar transformer, an antenna coil or a conductor pattern is formed on the substrate.